

## 25A, 150V N-CHANNEL MOSFET

#### **DESCRIPTION**

SVG15670NL5 is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan's LVMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance.

This device is widely used in power management for UPS and Inverter Systems.

#### **FEATURES**

- 25A, 150V,  $R_{DS(on)(typ.)} = 52m\Omega@V_{GS} = 10V$
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability
- 100% avalanche tested
- Pb-free lead plating
- RoHS compliant

# **KEY PERFORMANCE PARAMETERS**

Characteristics	Ratings	Unit
V <sub>DS</sub>	150	V
V <sub>GS(th)</sub>	2.0~5.0	V
R <sub>DS(on),max.</sub>	67	mΩ
I <sub>D.pulse</sub>	25	Α
Q <sub>g.typ.</sub>	8.9	nC

# sſ 8 D S 2 S 3 6 5 D PDFN-8-5X6X0.95-1.27

#### **ORDERING INFORMATION**

Part No.	Part No. Package		Hazardous Substance Control	Packing Type
SVG15670NL5TR	PDFN-8-5X6X0.95-1.27	15670NL5	Halogen free	Tape&Reel



### ABSOLUTE MAXIMUM RATINGS (UNLESS OTHERWISE NOTED, TJ=25°C)

Characteristics	Sumbal Test conditions		11			
	Symbol	Symbol Test conditions	Min.	Тур.	Max.	Unit
Drain-source Voltage	V <sub>DS</sub>		150			V
Gate-source Voltage	$V_{GS}$		-20		20	V
Desir Comment (Note 1)		T <sub>C</sub> =25°C			25	Α
Drain Current (Note 1)	Ι <sub>D</sub>	T <sub>C</sub> =100°C			16	Α
Drain Current Pulsed (Note 2)	I <sub>DM</sub>	T <sub>C</sub> =25°C			100	Α
Power Dissipation (Note 3)	P <sub>D</sub>	T <sub>C</sub> =25°C			89	W
Single Bulead Avalenche Energy	E <sub>AS</sub>	L=0.1mH, $V_{DD}$ =80V, $R_G$ =25 $\Omega$ ,			11	m l
Single Pulsed Avalanche Energy		starting temperature T <sub>J</sub> =25°C				mJ
Single Pulsed Current	I <sub>AS</sub>				15	Α
Operation Junction	т		55		150	00
Temperature Range	TJ		-55		150	°C
Storage Temperature Range	T <sub>stg</sub>		-55		150	°C

#### THERMAL CHARACTERISTICS

Characteristics	Symbol	Test conditions		Unit		
			Min.	Тур.	Max.	Oilit
Thermal Resistance,	D				1.4	0000
Junction-case, Bottom	$R_{ heta JC}$					°C/W
Thermal Resistance,	$R_{ heta JA}$	R <sub>0JA</sub>			50	°C AA
Junction-ambient						°C/W
Soldering Temperature (SMD)	T <sub>sold</sub>	Reflow soldering: 10 $\pm$ 1 sec,			260	00
		3times				°C

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#### ELECTRICAL CHARACTERISTICS (UNLESS OTHERWISE NOTED, TJ=25°C)

#### Static characteristics

Characteristics	Symbol	Test conditions	Ratings			Unit
Characteristics		rest conditions	Min.	Тур.	Max.	Offic
Drain-source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	150		1	V
Drain-Source Leakage Current	1	V <sub>DS</sub> =150V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	1		1.0	- μΑ
	I <sub>DSS</sub>	V <sub>DS</sub> =150V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	1	0.8	1	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	1		±100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{GS}=V_{DS}$ , $I_{D}=250\mu A$	2.0		5.0	V
Static Drain- Source	D <sub>not</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =4.1A	1	52	67	mΩ
On State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =6V, I <sub>D</sub> =3.3A	-	63	98	mΩ
Gate Resistance	$R_g$	f=1MHz		2.5		Ω

#### **Dynamic characteristics**

Characteristics	Cumbal	Symbol Test conditions	Ratings			1.1
Characteristics	Symbol		Min.	Тур.	Max.	Unit
Input Capacitance	C <sub>iss</sub>			518		
Output Capacitance	Coss	f=1MHz, V <sub>GS</sub> =0V, V <sub>DS</sub> =75V		76		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			3.3		
Turn-on Delay Time	t <sub>d(on)</sub>	V 75V V 40V D 000		8.2		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =75V, $V_{GS}$ =10V, $R_{G}$ =6.0 $\Omega$ ,		24		
Turn-off Delay Time	t <sub>d(off)</sub>	I <sub>D</sub> =4.1A (Notes 4.5)		13		ns
Turn-off Fall Time	t <sub>f</sub>	(Notes 4,5)		22		
Total Gate Charge	Qg			8.9		
Gate-source Charge	Q <sub>gs</sub>	V <sub>DD</sub> =75V, V <sub>GS</sub> =10V, I <sub>D</sub> =4.1A		3.9		nC
Gate-drain Charge	$Q_{gd}$	(Notes 4,5)		1.6		
Gate-plateau Voltage	V <sub>plateau</sub>			5.8		V

#### Reverse diode characteristics

Characteristics	Symbol Test co	Test conditions	Ratings			Unit
Onaracteristics	Symbol	rest conditions	Min.	Тур.	Max.	Offic
Continuous Source Current	Is	T <sub>C</sub> =25°C, Integral Reverse P-N	-	1	25	Α
Pulsed Source Current	I <sub>S,pulse</sub>	Junction Diode in the MOSFET	1	1	100	A
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> =2.0A, V <sub>GS</sub> =0V			1.4	V
Reverse Recovery Time	T <sub>rr</sub>	I <sub>S</sub> =4.1A, V <sub>GS</sub> =0V, V <sub>R</sub> =50V		60		ns
Reverse Recovery Charge	$Q_{rr}$	dI <sub>F</sub> /dt=100A/μs (Note 4)		110		nC

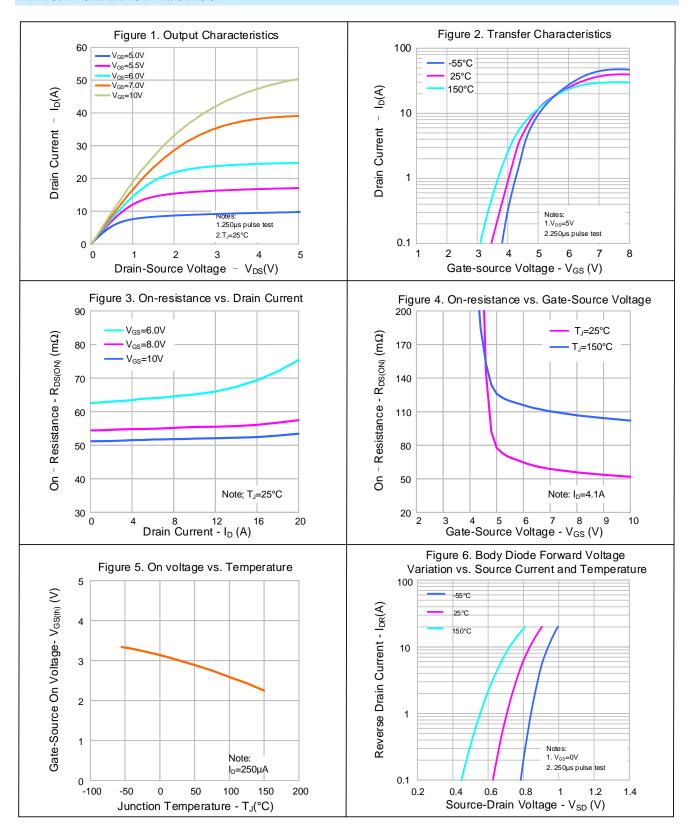
#### Notes:

- The rated value only refers to the maximum absolute value at 25°C (case temperature) in the datasheet, if the case temperature 1. is higher than 25 °C, it needs to be derated according to the actual environmental conditions
- 2.
- 3. The dissipation power will change with temperature, derating above 25°C: 0.71W/°C;
- 4. Pulse Test: Pulse width ≤300µs, Duty cycle≤2%;
- Essentially independent of operating temperature.

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#### TYPICAL CHARACTERISTICS

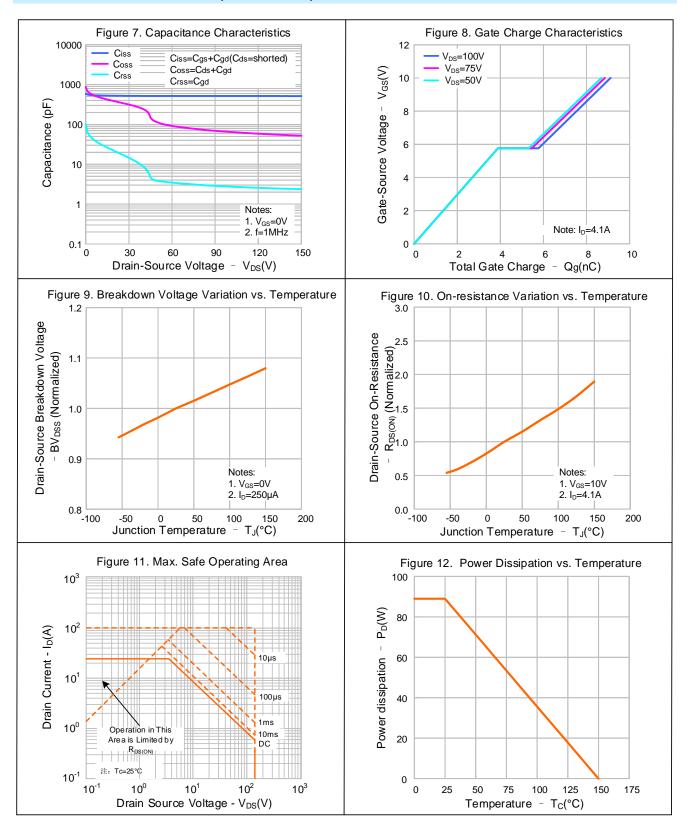


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#### **TYPICAL CHARACTERISTICS (CONTINUED)**

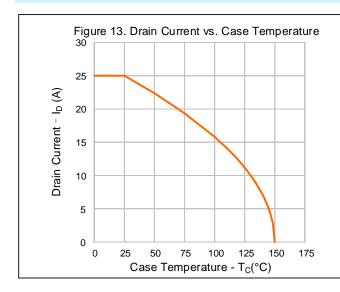


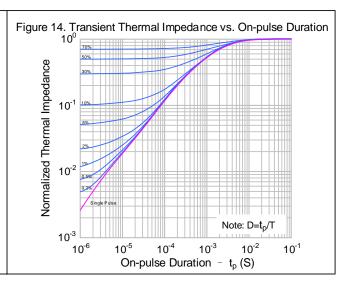
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#### **TYPICAL CHARACTERISTICS (CONTINUED)**



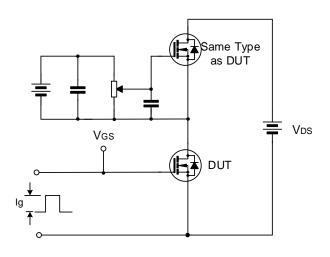


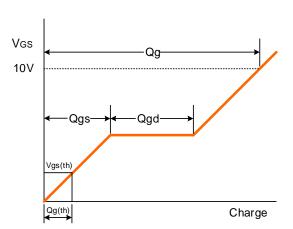
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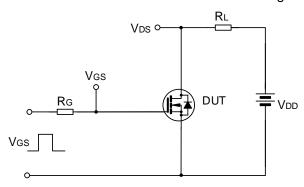
#### **TYPICAL TEST CIRCUIT**

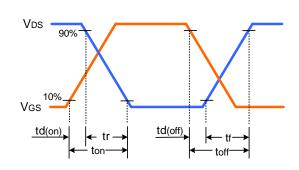
### Gate Charge Test Circuit & Waveform



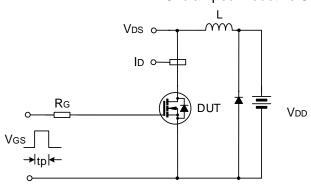


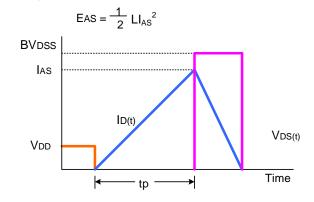
### Resistive Switching Test Circuit & Waveform





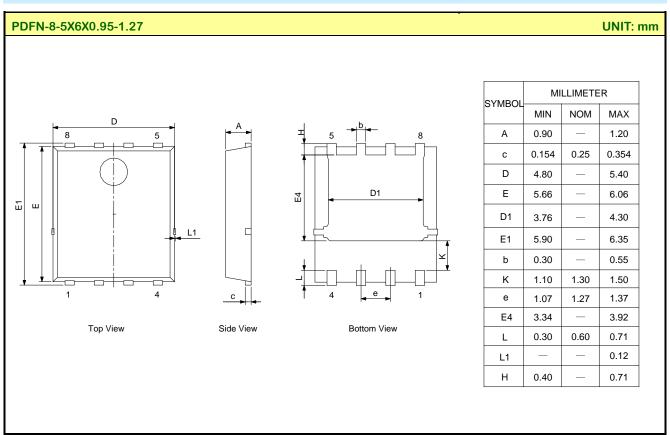
### Unclamped Inductive Switching Test Circuit & Waveform







#### **PACKAGE OUTLINE**





#### **MOS DEVICES OPERATE NOTES:**

Electrostatic charges may exist in many things. Please take following preventive measures to prevent effectively the MOS electric circuit as a result of the damage which is caused by discharge:

- The operator must put on wrist strap which should be earthed to against electrostatic.
- Equipment cases should be earthed.
- All tools used during assembly, including soldering tools and solder baths, must be earthed.
- MOS devices should be packed in antistatic/conductive containers for transportation.



### SVG15670NL5 Datasheet

#### Important notice:

- Silan reserves the right to make changes of this instruction without notice.
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# SVG15670NL5\_Datasheet

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